

DOCKET NO. EN995064BVUS4

D/#11 101/30/12

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Papathomas et al.)	Examiner: Berman, S	
Serial	No.: 09/771,275)	Art Unit: 1711	Echa M. Ca
Filed:	01/26/01)		Model To the
For:	r: LEAD PROTECTIVE COATING COMPOSITION, PROCESS AND STRUCTURE THEREOF			
Comn	nissioner for Patents			2,100

Sir:

Washington D.C. 20231

This paper is being filed in response to the Office Action dated April 24, 2002.

Reconsideration and allowance are respectfully requested in view of the Amendments and Remarks below.

<u>AMENDMENT</u>

Please cancel claims 25 and 26. Pending Claims 18-24 and new Claim 27 are as follows, wherein Claims 13 and 23 are amended and Claim 27 is new.

In The Claims

13 (THRICE AMENDED) A method for encapsulating a solder joint between an integrated circuit thip and a substrate, comprising the steps of:

forming a composition that includes a photoinitiator, a dispersed filler, and a resin precursor, wherein the resin precursor substantially consists of a cyanate ester monomer, a

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In Re Application Of: Page 1	apathomas et al.					
Serial No.	Filing Date	Examiner	Group Art Unit			
09/771,275	1/26/01	Berman, S.	1711			
Title: TENDEROTECTIVE COATING COMPOSITION, PROCESS AND STRUCTURE THEREOF						
TO THE ASSISTANT COMMISSIONER FOR PATENTS:						
	TO THE MODICINES. Ser.	///VIIOOIOITEITI OITI, /II	<u>s.</u>			
Transmitted herewith is: Amendment			RECEIVED RECHROLOGY CENTER TOO			
in the above identified ap	pplication.		1700			
 ☑ No additional fee is required. ☐ A check in the amount of is attached. ☑ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 09-0457(IBM) as described below. A duplicate copy of this sheet is enclosed. ☐ Charge the amount of ☑ Credit any overpayment. ☑ Charge any additional fee required. 						
Jack P. Friedman Reg. No. 44,688 Schmeiser, Olsen & Watts 3 Lear Jet Lane, Suite 201 Latham, NY 12110 (518) 220-1850	s	on 7/24/02 first class mail un	s document and fee is being deposited with the U.S. Postal Service as ider 37 C.F.R. 1.8 and is addressed to the issioner for Patents, Washington, D.C.			

CC:

Kim Dwileski

Typed or Printed Name of Person Mailing Correspondence